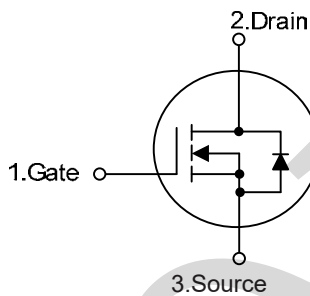
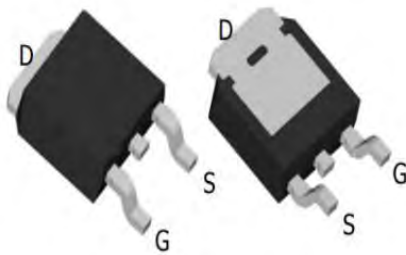


## SGT N-channel Power MOSFET

### MTR8R2N10D

#### TO-252



|                              |     |            |
|------------------------------|-----|------------|
| $V_{DS}$                     | 100 | V          |
| $R_{DS(on),TYP@ V_{GS}=10V}$ | 6.7 | m $\Omega$ |
| $I_D$                        | 82  | A          |

### Features

- 1、 Low on – resistance
- 2、 Package TO-252
- 3、 SGT Power MOSFET

### Applications

- 1、 Load Switch for Portable Devices
- 2、 DC/DC Converter

**Maximum ratings, at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

| Symbol   | Parameter                              |          | Rating     | Unit |
|----------|----------------------------------------|----------|------------|------|
| V(BR)DSS | Drain-Source breakdown voltage         |          | 100        | V    |
| VGS      | Gate-Source voltage                    |          | ±20        | V    |
| IAS      | Avalanche Current                      |          | 42         | A    |
| ID       | Continuous drain current @VGS=10V      | Tc=25°C  | 82         | A    |
|          |                                        | Tc=100°C | 52         | A    |
| IDM      | Pulse drain current tested ①           | Tc=25°C  | 246        | A    |
| EAS      | Avalanche energy, single pulsed ②      |          | 88         | mJ   |
| PD       | Maximum power dissipation              | Tc=25°C  | 104        | W    |
| TSTG,TJ  | Storage and Junction Temperature Range |          | -55 to 150 | °C   |

## Thermal Characteristics

| Symbol           | Parameter                               | Typical | Unit |
|------------------|-----------------------------------------|---------|------|
| R <sub>θJC</sub> | Thermal Resistance, Junction-to-Case    | 1.2     | °C/W |
| R <sub>θJA</sub> | Thermal Resistance, Junction-to-Ambient | 48      | °C/W |

## Electrical Characteristics

| Symbol | Parameter | Condition | Min. | Typ. | Max. | Unit |
|--------|-----------|-----------|------|------|------|------|
|--------|-----------|-----------|------|------|------|------|

Static Electrical Characteristics @T<sub>j</sub>=25°C (unless otherwise stated)

|                     |                                    |                                                          |     |     |      |    |
|---------------------|------------------------------------|----------------------------------------------------------|-----|-----|------|----|
| V(BR)DSS            | Drain-Source Breakdown Voltage     | V <sub>GS</sub> =0V, I <sub>D</sub> =250μA               | 100 | --  | --   | V  |
| I <sub>DSS</sub>    | Zero Gate Voltage Drain Current    | V <sub>DS</sub> =80V, V <sub>GS</sub> =0V                | --  | --  | 1    | μA |
| I <sub>GSS</sub>    | Gate-Body Leakage Current          | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V               | --  | --  | ±100 | nA |
| V <sub>GS(th)</sub> | Gate Threshold Voltage             | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA | 1.2 | 1.6 | 2.5  | V  |
| R <sub>DS(on)</sub> | Drain-Source On-State Resistance ④ | V <sub>GS</sub> =10V, I <sub>D</sub> =20A                | --  | 6.7 | 8.2  | mΩ |
|                     |                                    | V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A               | --  | 8.5 | 11   | mΩ |
| g <sub>fs</sub>     | Forward Transconductance           | V <sub>DS</sub> =5V, I <sub>D</sub> =20A                 | --  | 82  | --   | S  |

## Dynamic Electrical Characteristics@T<sub>j</sub> = 25°C (unless otherwise stated)

|                      |                              |                                                                     |    |      |    |    |
|----------------------|------------------------------|---------------------------------------------------------------------|----|------|----|----|
| C <sub>iss</sub>     | Input Capacitance            | V <sub>DS</sub> =50V, V <sub>GS</sub> =0V<br>, f=1MHz               | -- | 2360 | -- | pF |
| C <sub>oss</sub>     | Output Capacitance           |                                                                     | -- | 368  | -- | pF |
| C <sub>rss</sub>     | Reverse Transfer Capacitance |                                                                     | -- | 5.9  | -- | pF |
| R <sub>g</sub>       | Gate Resistance              | V <sub>DS</sub> =0V, V <sub>GS</sub> =0V ,<br>f=1MHz                | -- | 1.7  | -- | Ω  |
| Q <sub>g</sub> (10V) | Total Gate Charge            | V <sub>DS</sub> =75V, I <sub>D</sub> =20A ,<br>V <sub>GS</sub> =10V | -- | 34   | -- | nC |
| Q <sub>gs</sub>      | Gate-Source Charge           |                                                                     | -- | 5.4  | -- | nC |
| Q <sub>gd</sub>      | Gate-Drain Charge            |                                                                     | -- | 5.7  | -- | nC |

## Switching Characteristics

|         |                     |                                                                                                 |    |      |    |    |
|---------|---------------------|-------------------------------------------------------------------------------------------------|----|------|----|----|
| Td(on)  | Turn-on Delay Time  | V <sub>DS</sub> =75V,<br>V <sub>GS</sub> =10V,<br>R <sub>L</sub> =3.75Ω,<br>R <sub>G</sub> =6Ω, | -- | 8.4  | -- | ns |
| Tr      | Turn-on Rise Time   |                                                                                                 | -- | 12.2 | -- | ns |
| Td(off) | Turn-Off Delay Time |                                                                                                 | -- | 43   | -- | ns |
| Tf      | Turn-Off Fall Time  |                                                                                                 | -- | 18.9 | -- | ns |

## Source -Drain Diode Characteristics @T<sub>j</sub> = 25°C (unless otherwise stated)

|                 |                                 |                                         |    |     |     |    |
|-----------------|---------------------------------|-----------------------------------------|----|-----|-----|----|
| VSD             | Forward on voltage              | I <sub>S</sub> =1A, V <sub>GS</sub> =0V | -- | 0.7 | 1.0 | V  |
| I <sub>S</sub>  | Diode Forward Current           | T <sub>C</sub> = 25°C                   | -- | --  | 104 | A  |
| T <sub>rr</sub> | Reverse Recovery Time (Note1)   | I <sub>F</sub> =20A ,<br>di/dt=100A/μs  | -- | 51  | --  | ns |
| Q <sub>rr</sub> | Reverse Recovery Charge (Note1) |                                         | -- | 88  | --  | nC |

### NOTE:

- ① Computed continuous current assumes the condition of T<sub>J</sub>\_Max while the actual continuous current depends on the thermal & electro-mechanical application board design.
- ② This single-pulse measurement was taken under T<sub>J</sub>\_Max = 150°C.
- ③ This single-pulse measurement was taken under the following condition [L = 100μH, V<sub>GS</sub> = 10V, V<sub>DS</sub> = 50V] while its value is limited by T<sub>J</sub>\_Max = 150°C
- ④ The power dissipation PD is based on T<sub>J</sub>\_Max = 150°C.
- ⑤ This value is guaranteed by design hence it is not included in the production test.

## Typical Characteristics

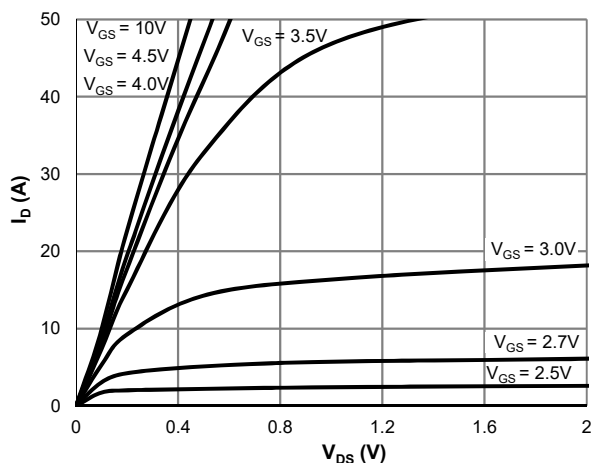


Figure 1: Saturation Characteristics

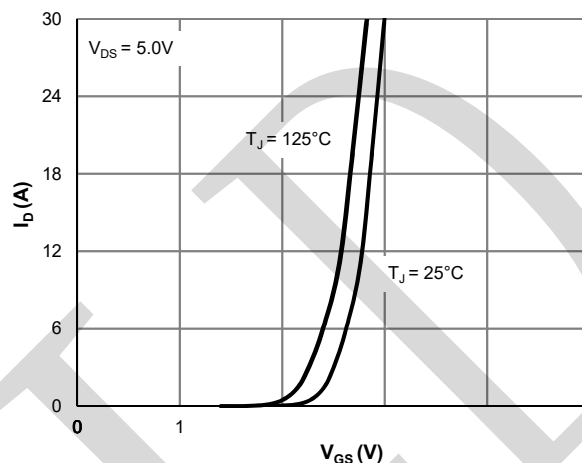


Figure 2: Transfer Characteristics

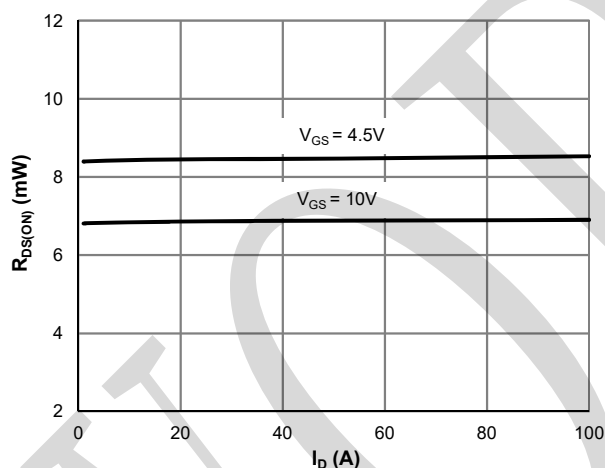


Figure 3:  $R_{DS(ON)}$  vs. Drain Current

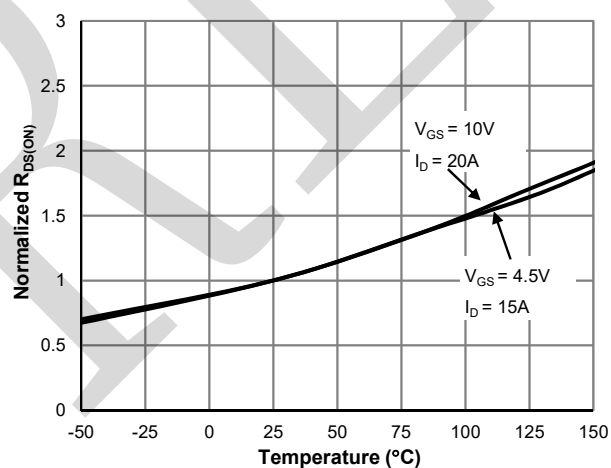


Figure 4:  $R_{DS(ON)}$  vs. Junction Temperature

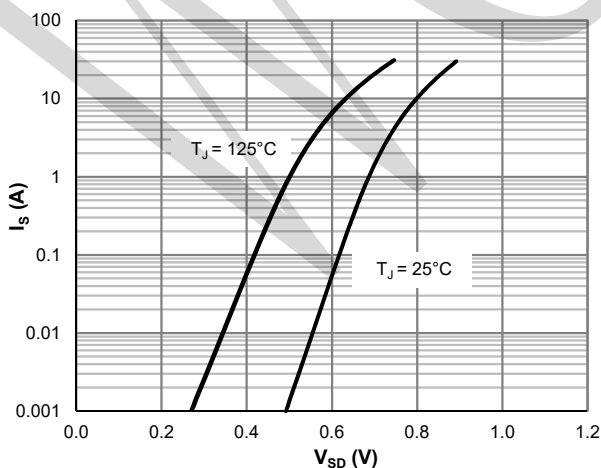


Figure 5: Body-Diode Characteristics

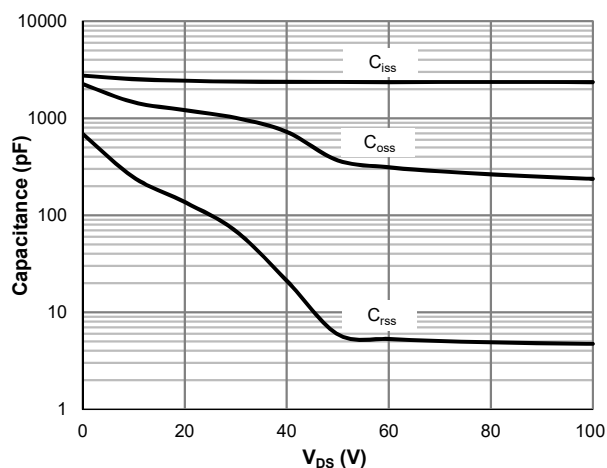


Figure 6: Capacitance Characteristics

## Typical Characteristics

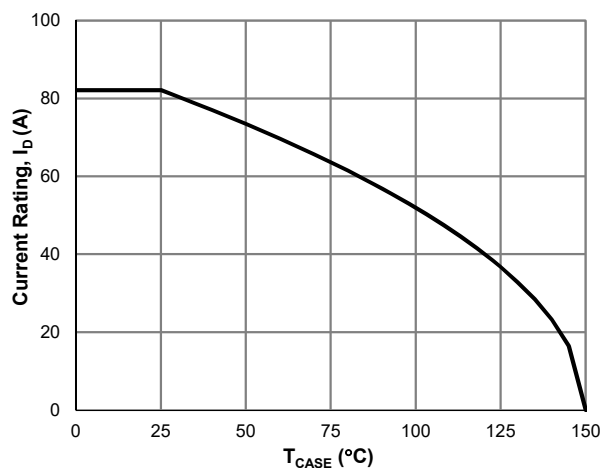


Figure 7: Current De-rating

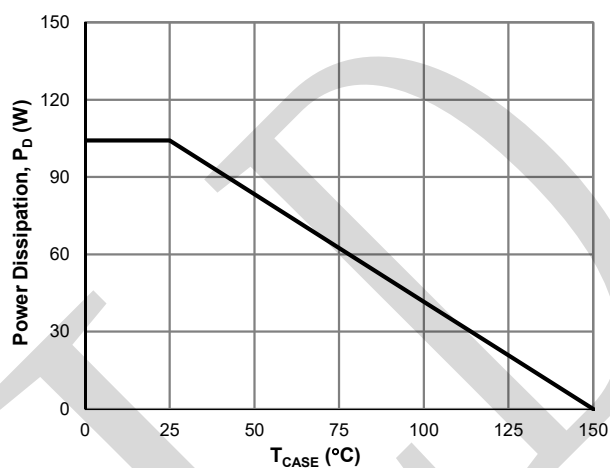


Figure 8: Power De-rating

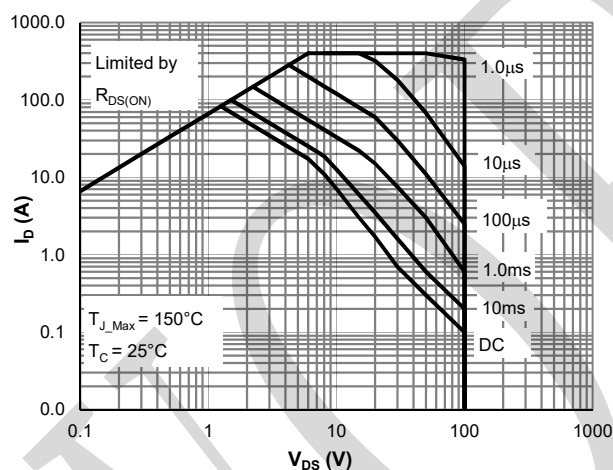


Figure 9: Maximum Safe Operating Area

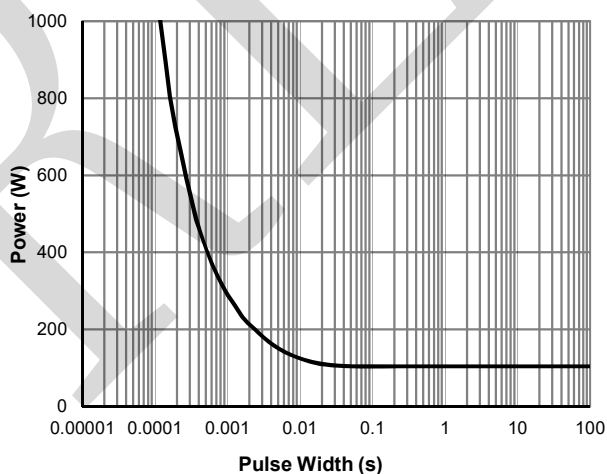


Figure 10: Single Pulse Power Rating, Junction-to-Case

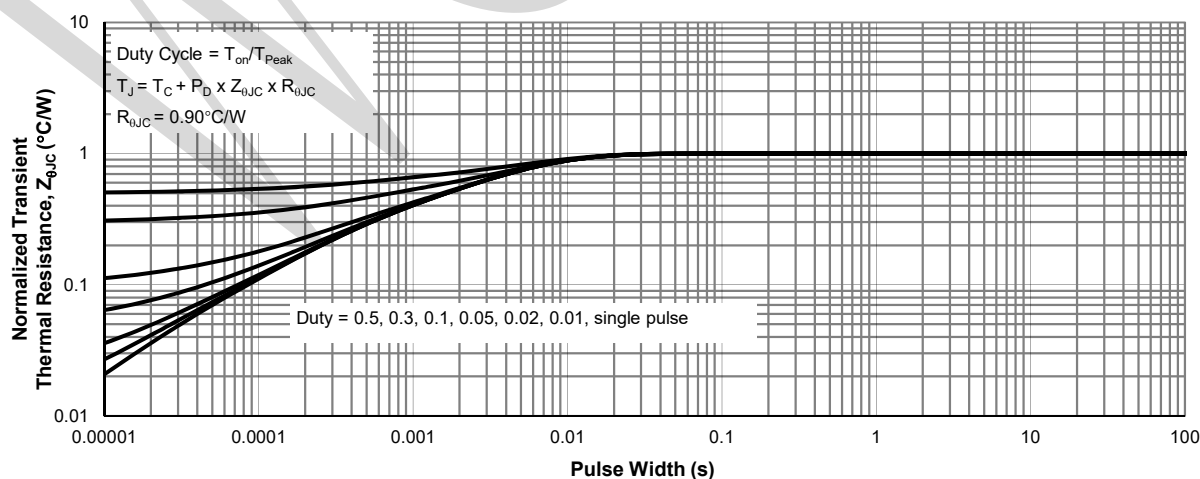


Figure 11: Normalized Maximum Transient Thermal Impedance

